MMBTH10L, MMBTH10-4L, SMMBTH10-4L, NSVMMBTH10L

VHF/UHF Transistor

NPN Silicon

Features

- S and NSV Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V _{CEO}	25	Vdc
Collector-Base Voltage	V_{CBO}	30	Vdc
Emitter-Base Voltage	V _{EBO}	3.0	Vdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction to Ambient (Note 1)	$R_{ heta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate (Note 2) T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction to Ambient (Note 2)	$R_{ heta JA}$	417	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

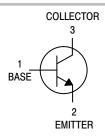
- 1. $FR-5 = 1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina



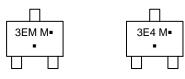
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MARKING DIAGRAMS



MMBTH10LT1G, NSVMMBTH10LT1G MMBTH10-04LT1G

3EM, 3E4= Specific Device Code

M = Date Code*

Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBTH10LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
NSVMMBTH10LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBTH10-4LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBTH10LT3G, SMMBTH10-4LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MMBTH10L, MMBTH10-4L, SMMBTH10-4L, NSVMMBTH10L

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS			•	•	-
Collector–Emitter Breakdown Voltage $(I_C = 1.0 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	25	_	-	Vdc
Collector–Base Breakdown Voltage (I _C = 100 μAdc, I _E = 0)	V _{(BR)CBO}	30	-	-	Vdc
Emitter–Base Breakdown Voltage $(I_E = 10 \mu Adc, I_C = 0)$	V _{(BR)EBO}	3.0	-	_	Vdc
Collector Cutoff Current (V _{CB} = 25 Vdc, I _E = 0)	Ісво	-	-	100	nAdc
Emitter Cutoff Current (V _{EB} = 2.0 Vdc, I _C = 0)	I _{EBO}	-	_	100	nAdc
ON CHARACTERISTICS			•	•	-
DC Current Gain ($I_C = 4.0$ mAdc, $V_{CE} = 10$ Vdc) MMBTH10LT1G, NSVMMBTH10LT1G MMBTH10-4LT1G, SMMBTH10-4LT3G	h _{FE}	60 120	_ _	_ 240	-
Collector–Emitter Saturation Voltage (I _C = 4.0 mAdc, I _B = 0.4 mAdc)	V _{CE(sat)}	_	_	0.5	Vdc
Base–Emitter On Voltage (I _C = 4.0 mAdc, V _{CE} = 10 Vdc)	V _{BE}	-	-	0.95	Vdc
SMALL-SIGNAL CHARACTERISTICS			•		•
Current–Gain – Bandwidth Product (I _C = 4.0 mAdc, V _{CE} = 10 Vdc, f = 100 Mhz) MMBTH10LT1G, NSVMMBTH10LT1G MMBTH10–4LT1G, SMMBTH10–4LT3G	f _T	650 800	_ _	_ _	MHz
Collector–Base Capacitance $(V_{CB}=10 \text{ Vdc}, I_E=0, f=1.0 \text{ MHz})$	C _{cb}	-	-	0.7	pF
Common–Base Feedback Capacitance (V _{CB} = 10 Vdc, I _E = 0, f = 1.0 MHz)	C _{rb}	-	-	0.65	pF
Collector Base Time Constant (I _C = 4.0 mAdc, V _{CB} = 10 Vdc, f = 31.8 MHz)	rb′C _c	-	-	9.0	ps

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

MMBTH10L, MMBTH10-4L, SMMBTH10-4L, NSVMMBTH10L

TYPICAL CHARACTERISTICS

COMMON-BASE y PARAMETERS versus FREQUENCY

 $(V_{CB} = 10 \text{ Vdc}, I_{C} = 4.0 \text{ mAdc}, T_{A} = 25^{\circ}\text{C})$

yib, INPUT ADMITTANCE

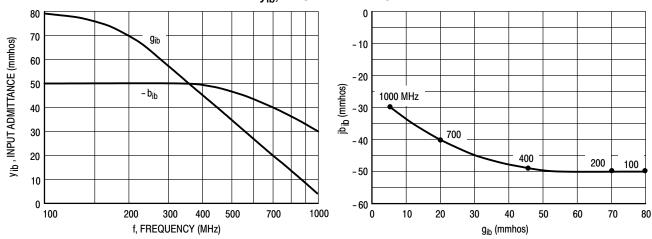


Figure 1. Rectangular Form

Figure 2. Polar Form

y_{fb}, FORWARD TRANSFER ADMITTANCE

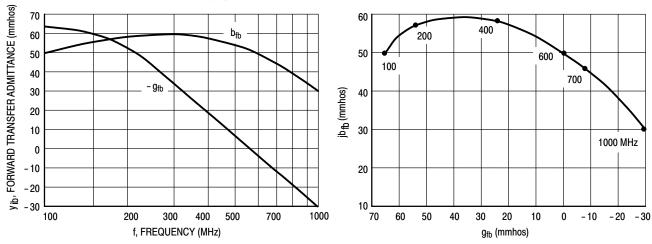


Figure 3. Rectangular Form

Figure 4. Polar Form

MMBTH10L, MMBTH10-4L, SMMBTH10-4L, NSVMMBTH10L

TYPICAL CHARACTERISTICS

COMMON-BASE y PARAMETERS versus FREQUENCY

 $(V_{CB} = 10 \text{ Vdc}, I_C = 4.0 \text{ mAdc}, T_A = 25^{\circ}\text{C})$

y_{rb}, REVERSE TRANSFER ADMITTANCE

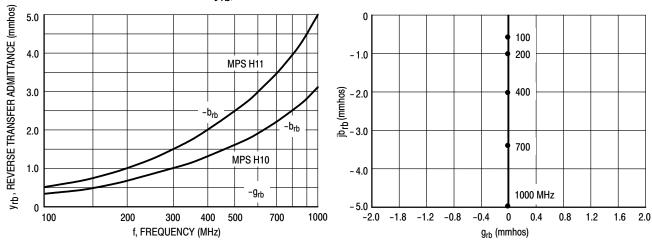


Figure 5. Rectangular Form

Figure 6. Polar Form

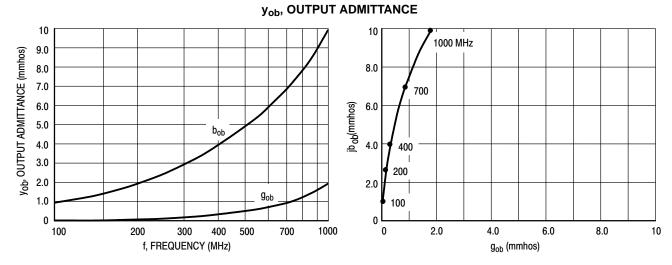


Figure 7. Rectangular Form

Figure 8. Polar Form

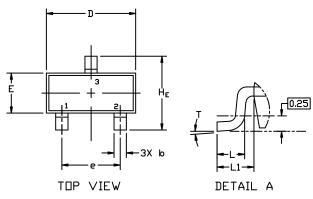


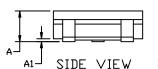


SOT-23 (TO-236) CASE 318 ISSUE AT

DATE 01 MAR 2023









NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS		INCHES			
DIM	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
Ε	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0*		10°	0*		10°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

M = Date Code

■ = Pb-Free Package



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

STYLES ON PAGE 2

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^{*}This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SOT-23 (TO-236) CASE 318 ISSUE AT

DATE 01 MAR 2023

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE	1	
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	STYLE 11: PIN 1. ANODE 2. CATHODE 3. CATHODE-ANODE	STYLE 12: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 13: PIN 1. SOURCE 2. DRAIN 3. GATE	STYLE 14: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE	STYLE 17: PIN 1. NO CONNECTION 2. ANODE 3. CATHODE	STYLE 18: PIN 1. NO CONNECTION 2. CATHODE 3. ANODE	STYLE 19: N PIN 1. CATHODE 2. ANODE 3. CATHODE-ANODE	STYLE 20: PIN 1. CATHODE 2. ANODE 3. GATE
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT	STYLE 23: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 24: PIN 1. GATE 2. DRAIN 3. SOURCE	STYLE 25: PIN 1. ANODE 2. CATHODE 3. GATE	STYLE 26: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

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